

**IN THE CLAIMS:**

Please amend claims 9 and 17 as follows:

1. (Original) Apparatus for electro-chemical deposition on a substrate, comprising:
  - an annular conductive body adapted to support the substrate and having at least one pin receiving pocket formed therein; and
  - at least one electrical contact pin having a portion brazed in the receiving pocket, the contact pin adapted to electrically bias the substrate.
2. (Original) The apparatus of claim 1, wherein the contact pin is an annular ring.
3. (Original) The apparatus of claim 1, wherein the contact pin is a plurality of arc segments.
4. (Original) The apparatus of claim 1, wherein the contact pin is a plurality of cylindrical posts.
5. (Original) The apparatus of claim 1, wherein the conductive body further comprises:
  - a first surface;
  - a shoulder coupled to the first surface; and
  - a substrate support surface extending inward from the shoulder and supporting the electrical contact pin thereon, the substrate support surface and shoulder defining a substrate receiving pocket.
6. (Original) The apparatus of claim 1, wherein the contact pin is comprised platinum or platinum alloy.

7. (Original) The apparatus of claim 1 further comprising:  
a dielectric covering at least partially encapsulating the conductive body.

8. (Original) The apparatus of claim 7, wherein the contact pin further comprises:  
a portion extending from the conductive body and having a contact surface free from the dielectric covering.

9. (Currently Amended) Apparatus for electro-chemical deposition on a substrate, comprising:  
an annular conductive body adapted to support the substrate and having at least one pin receiving pocket formed therein;  
at least one electrical contact pin having a portion brazed in the receiving pocket slot, the contact pin adapted to electrical electrically bias the substrate proximate the substrate's perimeter; and  
a first seal disposed inward of the electrical contact pin and providing a seal with the conductive body.

10. (Original) The apparatus of claim 9, wherein the contact pin is an annular ring.

11. (Original) The apparatus of claim 9, wherein the contact pin is a plurality of arc segments.

12. (Original) The apparatus of claim 9, wherein the contact pin is a plurality of cylindrical posts.

13. (Original) The apparatus of claim 9, wherein the conductive body further comprises:  
a first surface;  
a shoulder coupled to the first surface;

a substrate support surface extending inward from the shoulder and supporting the electrical contact pin thereon, the substrate support surface and shoulder defining a substrate receiving pocket; and

an inner ring surface disposed radially inward of the substrate support surface, the inner ring surface in sealing communication with the first seal.

14. (Original) The apparatus of claim 9, wherein the contact pin is comprised platinum or platinum alloy.

15. (Original) The apparatus of claim 9 further comprising:

a dielectric covering at least partially encapsulating the conductive body.

16. (Original) The apparatus of claim 15, wherein the contact pin further comprises:

a portion extending from the conductive body and having a contact surface free from the dielectric covering.

17. (Currently Amended) Apparatus for electro-chemical deposition on a substrate, comprising:

an annular conductive body adapted to support the substrate and having at least one pin receiving pocket formed therein;

a dielectric covering at least partially encapsulating the conductive body; and

at least one electrical contact pin having a portion brazed in the receiving pocket, the contact pin adapted to electrical electrically bias the substrate proximate the substrate's perimeter and having an exposed portion extending from the conductive body and having a contact surface free from the dielectric covering.

Claims 18-36 (Canceled)